

IEEE Transactions in Power Electronics IEEE Transactions in Industry Applications

Joint Special Issue on Power Electronics in Emerging Applications, 2012

Scheduled Publication Time: March 2012

Power electronics has matured as an enabling technology for a wide variety of applications from industrial to transportation to commercial to appliances and to energy efficiency. The technology has evolved tremendously to approach the physical limits of standard applications in dynamics and energy performance. The challenge in the coming years lies in developing new techniques at the lowest possible cost for emerging applications, to which the special Issue is dedicated.

Prospective authors are invited to submit original contributions, or survey papers or tutorials, for review for publication in this joint special issue on Power Electronics in Emerging Applications. Topics of interest include, but are not limited to:

- Solid-state lighting
- Wireless energy transfer
- Power supply on chip
- Intelligent dc/dc power distribution (Nano or Micro Grids)
- Wireless remote sensing node
- Energy harvesting
- Hardware in a loop
- Novel transportation technologies

Papers with applications in nature are particularly welcome. Papers submitted for presentation at ECCE2011 are also welcome.

All manuscripts must be submitted through Manuscript Central at <http://mc.manuscriptcentral.com/tpele-ieee>. Submissions must be clearly marked "Special Issue on Power Electronics, 2012" or "Special Issue on Industry Applications, 2012" on the cover page. When uploading your paper, please indicate, under step 4 – *Details & Comments*, that it is for the "Special Issue on Power Electronics in Emerging Applications, 2012." Refer to <http://www.pels.org> for general information about electronic submission through Manuscript Central. Manuscripts submitted for the special issue will be reviewed separately and will be handled by the guest editorial board noted below.

Deadline for Submission of Manuscript: September 1, 2011

Guest Co-Editor: F. Dong Tan, Northrop Grumman Aerospace Systems (dong.tan@ngc.com)

Guest Co-Editor: Giovanna Oriti, Naval Postgraduate School (giovanna.oriti@ieee.org)

The Guest Associate Editors:

- | | |
|--|---|
| • Y-F. Liu, Queen's University, Canada | • A. Emadi, Illinois Tech, USA |
| • A. Consoli, University of Catania, Italy | • John Shen, U of Central Florida, USA |
| • T. Sebastian, Nexteer, Inc., USA | • Cian O'Mathuna, Tyndall National, Ireland |
| • B. Lequesne, Eaton Inc., USA | • Henry Chung, City U, Hong Kong, China |
| • D. Borojevic, Virginia Tech, USA | • Michael Harke, Danfoss, USA |
| • Liuchen Chang, UNF, Canada | • Y-S Lai, Taipei U of Tech, Taiwan |
| • J. Cobos, UPM, Spain | • H-J Chiu, Taiwan U, Taiwan |
| • R. Hui, City U, Hong Kong, China | • David Perreault, MIT, USA |
| • D. Maksimovic, University of Colorado, USA | • Jain Sun, Resenlear Institute of Tech |
| • S. Sanders, UC Berkeley, USA | • Hideaki Fujita, Tokyo Institute of Tech |
| • B. Lehman, Northeastern University, USA | |

Proposed Timeline:

- | | |
|----------------|--|
| • Mar 10, 2011 | – Proposal Approval by PELS AdCom and IAS Board |
| • Apr, 1 2011 | – Call for Papers in the Transactions and Newsletter |
| • Sep 1, 2011 | – Manuscripts Submission Deadline |
| • Oct 1, 2011 | – First Review Complete |
| • Oct 15, 2011 | – Revised Manuscripts Due |
| • Nov 15, 2011 | – Final Acceptance Notification |
| • Dec 24, 2011 | – Final Manuscripts Due |
| • Jan 31, 2012 | – Manuscripts Forwarded to IEEE for Publication |
| • Mar, 2012 | – Special Issue Appears in Transactions |